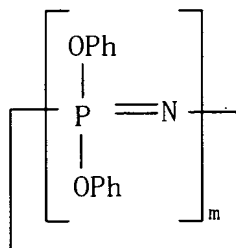


ABSTRACT OF THE DISCLOSURE

A heat-resistant composition contains solvent-soluble polyimide resin (A) and a phosphazene compound (B) in relation to a polyimide resin composition having solubility in a low-boiling solvent, heat resistance, flame resistance, adhesiveness and mechanical properties. The said phosphazene compound (B) is a cyclic phenoxyphosphazene compound (B1) expressed in the following chemical formula (1):



(1)

where m represents an integer of 3 to 25 and Ph represents a phenyl group.